

ABSTRACT OF THE DISCLOSURE

A method for fabrication of microelectromechanical systems (MEMS) integrated micro devices and acceleration sensor devices formed according to the method, the method being micromachining an array of first three-dimensional micromechanical device features in a first silicon wafer; micromachining an array of second three-dimensional micromechanical device features in a second silicon wafer, wherein the second three-dimensional micromechanical device features are configured to cooperate with the first three-dimensional micromechanical device features when joined therewith; mutually aligning the first and second arrays of device features by aligning the first and second wafers; permanently joining the first and second arrays of device features into an array of integrated micro devices as a function of permanently joining the first and second wafers into a single composite wafer; and subsequently separating the array of integral devices into individual devices each having a set of the first and second device features.